

L Number	Hits	Search Text	DB	Time stamp
-	210	((257/684 257/796 257/666 257/669 257/670 257/671 257/672 257/674 257/676 257/758 257/690 257/692 257/693 257/696 257/698 257/784 257/787) and (semiconductor adj devices)) and (tie adj bar)	USPAT	2002/01/30 15:18
-	64	((257/684 257/796 257/666 257/669 257/670 257/671 257/672 257/674 257/676 257/758 257/690 257/692 257/693 257/696 257/698 257/784 257/787) and (semiconductor adj devices)) and suspending	USPAT	2002/01/30 15:06
-	3105	(257/684 257/796 257/666 257/669 257/670 257/671 257/672 257/674 257/676 257/758 257/690 257/692 257/693 257/696 257/698 257/784 257/787) and (semiconductor adj devices)	USPAT	2002/01/30 15:04
-	6916	(257/684 257/796 257/666 257/669 257/670 257/671 257/672 257/674 257/676 257/758 257/690 257/692 257/693 257/696 257/698 257/784 257/787) and semiconductor	USPAT	2002/01/30 15:03
-	8599	257/684 257/796 257/666 257/669 257/670 257/671 257/672 257/674 257/676 257/758 257/690 257/692 257/693 257/696 257/698 257/784 257/787	USPAT	2002/01/30 14:57
-	1630	257/787	USPAT	2002/01/30 14:57
-	1003	257/784	USPAT	2002/01/30 14:56
-	1127	257/698	USPAT	2002/01/30 14:56
-	579	257/696	USPAT	2002/01/30 14:56
-	1067	257/693	USPAT	2002/01/30 14:56
-	1461	257/692	USPAT	2002/01/30 14:56
-	1122	257/690	USPAT	2002/01/30 14:56
-	1983	257/758	USPAT	2002/01/30 14:56
-	1467	257/676	USPAT	2002/01/30 14:56
-	334	257/674	USPAT	2002/01/30 14:56
-	434	257/672	USPAT	2002/01/30 14:55
-	174	257/671	USPAT	2002/01/30 14:55
-	394	257/670	USPAT	2002/01/30 14:55
-	537	257/669	USPAT	2002/01/30 14:55
-	2023	257/666	USPAT	2002/01/30 14:55
-	615	257/796	USPAT	2002/01/30 14:55
-	496	257/684	USPAT	2002/01/30 14:55
-	496	257/684	USPAT	2002/01/31 08:57
-	615	257/796	USPAT	2002/01/31 09:06
-	2023	257/666	USPAT	2002/01/31 09:06
-	537	257/669	USPAT	2002/01/31 09:06
-	394	257/670	USPAT	2002/01/31 09:06
-	174	257/671	USPAT	2002/01/31 09:06
-	434	257/672	USPAT	2002/01/31 09:06
-	334	257/674	USPAT	2002/01/31 09:07
-	1467	257/676	USPAT	2002/01/31 09:07
-	1278	257/678	USPAT	2002/01/31 09:07
-	1122	257/690	USPAT	2002/01/31 09:07
-	1461	257/692	USPAT	2002/01/31 09:07
-	1067	257/693	USPAT	2002/01/31 09:07
-	579	257/696	USPAT	2002/01/31 09:07
-	1127	257/698	USPAT	2002/01/31 09:07
-	1003	257/784	USPAT	2002/01/31 09:07
-	1630	257/787	USPAT	2002/01/31 09:10
-	7396	257/684 257/796 257/666 257/669 257/670 257/671 257/672 257/674 257/676 257/678 257/690 257/692 257/693 257/696 257/698 257/784 257/787	USPAT	2002/01/31 09:12
-	4	(257/684 257/796 257/666 257/669 257/670 257/671 257/672 257/674 257/676 257/678 257/690 257/692 257/693 257/696 257/698 257/784 257/787) and (grid adj lead)	USPAT	2002/01/31 09:17

-	0	(257/684 257/796 257/666 257/669 257/670 257/671 257/672 257/674 257/676 257/678 257/690 257/692 257/693 257/696 257/698 257/784 257/787) and (grid adj lead) and (tie adj bars) and (semiconductor adj devices)	USPAT	2002/01/31 09:18
-	1076	(257/684 257/796 257/666 257/669 257/670 257/671 257/672 257/674 257/676 257/678 257/690 257/692 257/693 257/696 257/698 257/784 257/787) and (lead adj frames)	USPAT	2002/01/31 09:34
-	464164	(((((257/684 257/796 257/666 257/669 257/670 257/671 257/672 257/674 257/676 257/678 257/690 257/692 257/693 257/696 257/698 257/784 257/787) and (lead adj frames)) and matrix) and (semiconductor adj devices)) and suspending) and molding compound	USPAT	2002/01/31 09:36
-	22	(((((257/684 257/796 257/666 257/669 257/670 257/671 257/672 257/674 257/676 257/678 257/690 257/692 257/693 257/696 257/698 257/784 257/787) and (lead adj frames)) and matrix) and (semiconductor adj devices)) and suspending	USPAT	2002/01/31 09:37
-	1	(((((257/684 257/796 257/666 257/669 257/670 257/671 257/672 257/674 257/676 257/678 257/690 257/692 257/693 257/696 257/698 257/784 257/787) and (lead adj frames)) and matrix) and (semiconductor adj devices)) and suspending) and (molding adj compound)	USPAT	2002/01/31 09:46
-	75	((((257/684 257/796 257/666 257/669 257/670 257/671 257/672 257/674 257/676 257/678 257/690 257/692 257/693 257/696 257/698 257/784 257/787) and (lead adj frames)) and matrix) and (semiconductor adj devices)	USPAT	2002/01/31 09:46
-	114	((257/684 257/796 257/666 257/669 257/670 257/671 257/672 257/674 257/676 257/678 257/690 257/692 257/693 257/696 257/698 257/784 257/787) and (lead adj frames)) and matrix	USPAT	2002/01/31 09:58
-	0	(terminal adj lead) and (edge adj package) and (semiconductor adj devices) and (tie adj bars) and (suspending)	USPAT	2002/02/01 10:20
-	1	(terminal adj lead) and (edge adj package) and (semiconductor adj devices) and (tie adj bars) and 257/\$7.ccls.	USPAT	2002/02/01 11:32
-	579	257/696	USPAT	2002/02/01 11:32
-	1023	257/684 257/696	USPAT	2002/02/01 11:33
-	1015528	(257/684 257/696) amd (terminal leads)	USPAT	2002/02/01 11:33
-	57	(257/684 257/696) and (terminal adj leads)	USPAT	2002/02/01 11:33
-	363	(257/684 257/696) and (semiconductor adj devices)	USPAT	2002/02/01 11:33
-	66	(257/684 257/696) and (tie adj bars)	USPAT	2002/02/01 11:34
-	8	(257/684 257/696) and (suspending adj lead)	USPAT	2002/02/01 11:35
-	0	(257/684 257/696) and (terminal adj leads) and (semiconductor adj devices) and (tie adj bars) and (suspending)	USPAT	2002/02/01 11:36
-	420	((257/684 257/696) and (terminal adj leads)) ((257/684 257/696) and (semiconductor adj devices)) ((257/684 257/696) and (tie adj bars)) ((257/684 257/696) and (suspending adj lead))	USPAT	2002/02/01 11:37
-	1	(257/684 257/696) and (molding adj compound) and (suspending) and (semiconductor adj devices)	USPAT	2002/02/01 15:57

-	0	("US 5665651 A".DID. and ("US 5606204 A".DID. and ("US 6020625 A".DID. and ((257/684 257/696) and (terminal adj leads)) ((257/684 257/696) and (semiconductor adj devices)) ((257/684 257/696) and (tie adj bars)) ((257/684 257/696) and (suspending adj lead)))) and (semiconductor adj devices) and (tie adj bars) and (terminal adj lead))) and (semiconductor adj devices))) and (lead adj frame)	USPAT	2002/02/01 15:57
-	0	((257/684 257/696) and (molding adj compound) and (suspending) and (semiconductor adj devices)) and (lead adj frame)	USPAT	2002/02/01 15:58
-	13	(tie adj bars) and (semiconductor adj devices) and (suspending)	USPAT	2002/02/01 16:01
-	496	257/684	USPAT	2002/02/05 10:16
-	1006	257/784	USPAT	2002/02/05 10:16
-	1634	257/787	USPAT	2002/02/05 10:16
-	504	257/788	USPAT	2002/02/05 10:16
-	616	257/796	USPAT	2002/02/05 10:16
-	866	257/701	USPAT	2002/02/05 10:16
-	222	257/708	USPAT	2002/02/05 10:16
-	161	257/709	USPAT	2002/02/05 10:16
-	1811	257/723	USPAT	2002/02/05 10:16
-	1358	257/724	USPAT	2002/02/05 10:16
-	278	257/729	USPAT	2002/02/05 10:16
-	510	257/730	USPAT	2002/02/05 10:16
-	219	257/731	USPAT	2002/02/05 10:16
-	147	257/732	USPAT	2002/02/05 10:17
-	206	257/733	USPAT	2002/02/05 10:17
-	1474	257/676	USPAT	2002/02/05 10:17
-	489	257/782	USPAT	2002/02/05 10:17
-	741	257/783	USPAT	2002/02/05 10:17
-	1872	257/773	USPAT	2002/02/05 10:18
-	9080	257/784 257/787 257/788 257/796 257/701 257/704 257/708 257/709 257/710 257/723 257/724 257/729 257/730 257/731 257/732 257/733 257/676 257/782 257/783 257/773	USPAT	2002/02/05 10:23
-	6658	(257/784 257/787 257/788 257/796 257/701 257/704 257/708 257/709 257/710 257/723 257/724 257/729 257/730 257/731 257/732 257/733 257/676 257/782 257/783 257/773) and (shield lid top cover cap)	USPAT	2002/02/05 10:25
-	4574	((257/784 257/787 257/788 257/796 257/701 257/704 257/708 257/709 257/710 257/723 257/724 257/729 257/730 257/731 257/732 257/733 257/676 257/782 257/783 257/773) and (shield lid top cover cap)) and (molding encapsulation passivation insulating)	USPAT	2002/02/05 10:26
-	1528	((((257/784 257/787 257/788 257/796 257/701 257/704 257/708 257/709 257/710 257/723 257/724 257/729 257/730 257/731 257/732 257/733 257/676 257/782 257/783 257/773) and (shield lid top cover cap)) and (molding encapsulation passivation insulating)) and electrode) and device	USPAT	2002/02/05 10:28
-	483	(((((257/784 257/787 257/788 257/796 257/701 257/704 257/708 257/709 257/710 257/723 257/724 257/729 257/730 257/731 257/732 257/733 257/676 257/782 257/783 257/773) and (shield lid top cover cap)) and (molding encapsulation passivation insulating)) and electrode) and device) and (capacitor resistors)	USPAT	2002/02/05 10:41